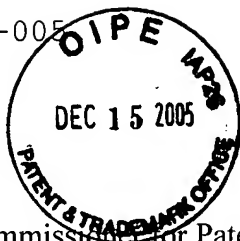


JW



December 12, 2005

To: Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Fr: Stephen B. Ackerman, Reg. No. 37,761  
28 Davis Avenue  
Poughkeepsie, N.Y. 12603

Subject:

Serial No.	10/796,427	03/09/04
MOU-SHIUNG LIN		
"WIREBOND PAD FOR SEMICONDUCTOR CHIP OR WAFER"		
Grp. Art Unit: 2822	LEWIS, MONICA	

## RESPONSE TO FINAL OFFICE ACTION

Dear Sir:

In response to the Office Action mailed September 12, 2005, please consider the remarks  
as follows:

## CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on December 12, 2005.

Stephen B. Ackerman, Reg. No. 37,761

Signature

A handwritten signature in dark ink, appearing to be "S. B. Ackerman", written over a horizontal line.

Date

12/12/05